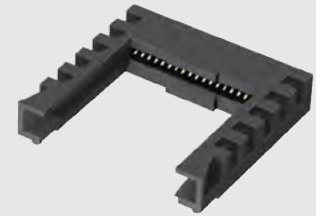


MB1-130-01-F-S-01-SL-N



(1.00 mm) .0394"

MB1 SERIES

MINI EDGE CARD SOCKET WITH GUIDES

Mates with:
 (0.80 mm) .031" PCB,
 (1.60 mm) .062" PCB

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MB1

Insulator Material: Black LCP
Contact Material: BeCu
Plating: Sn or Au over 50 μm (1.27 μm) Ni
Current Rating: 2.2 A per pin (6 pins powered)
Operating Temp Range: -55 °C to +125 °C
Insertion Depth: (5.26 mm) .207" to (6.10 mm) .240"
RoHS Compliant: Yes

PROCESSING

Lead-Free Solderable: Yes
SMT Lead Coplanarity: (0.10 mm) .004" max (20-30) (0.15 mm) .006" max (40-50)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



Notes:
 Patented

Some sizes, styles and options are non-standard, non-returnable.

MB1
1
NO. OF PINS
01
PLATING OPTION
S
CARD SLOT
SL
OTHER OPTION

20, 30, 40, 50

(No. of Positions + 2) x (1.00) .03937 + (4.06) .160

-F

= Gold flash on contact, Matte Tin on tail

-L

= 10 μm (0.25 μm) Gold on contact, Matte Tin on tail

Specify CARD SLOT from chart

CARD SLOT	A	MATES WITH BOARD THICKNESS
-01	(0.97) .038	(0.80) .031
-02	(1.83) .072	(1.60) .062

-N

= No Card Guides

-N OPTION

ALSO AVAILABLE (MOQ Required)

- Other platings

Contact Samtec.

Important Note: Samtec recommends that pads on the mating board be Gold plated.

OTHER SOLUTIONS

Flex Card System

- .050" (1.27 mm) (FCF/EMF Series) systems
- Vertical and horizontal
- Header with snap-on card guides for design flexibility
- Elevated design now available
- Ideal for multiple add-on cards
- Solder locks for mechanical stability
- Any size from 40 to 100 contacts

